

APPROVAL SHEET

RGTCM Series – 0806(3025)- RoHS Compliance

THIN FILM CERAMIC COMMON MODE FILTER

Halogens Free Product

P/N: RGTCM0806650H0T

*Contents in this sheet are subject to change without prior notice.



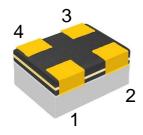
FEATURES

- 1. Miniature footprint: 0.8 X 0.6 X 0.5 mm³.
- 2. Thin Film Technology.
- 3. Reflow Solderable SMD Devices.
- 4. Wide Pass Band(Cut- Off Frequency: -3dB : 4/5/8GHz Typical).
- 5. High attenuation for common mode noise.
- 6. This product contains no lead and supports lead-free Ni/Au soldering

APPLICATIONS

- 1. For Super Speed Signal Line Application
- 2. LVDS/IEEE1394/HDMI/DVI/MIPI/USB3.0

CONSTRUCTION



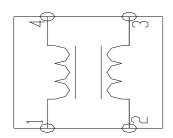


DIMENSIONS

Figure	Symbol	Dimension (mm)
W T B	L	0.88 ± 0.05
	W	0.68 ± 0.05
	Т	0.50 ± 0.05
	А	0.15 ± 0.05
	В	0.20 ± 0.05
A	С	0.27 ± 0.10
	D	0.62 ± 0.05
	E	0.50 ± 0.10
	F	0.82 ± 0.05



EQUIVALENT CIRCUIT



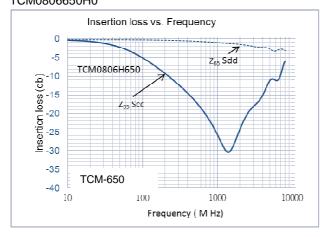
ELECTRICAL CHARACTERISTICS

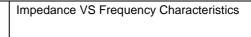
Туре	Common Mode Impedance (Ω)	Max. DC Resistance (Ω)	Rated Current (mA)	Rated Voltage Ed(V)	Cut off Frequency (GHz) typ.	Insulation Resistance (M Ω) min.
RGTCM0806650H0T	65±20%	2.5±30%	100	10	5G	10

Typical electrical performance

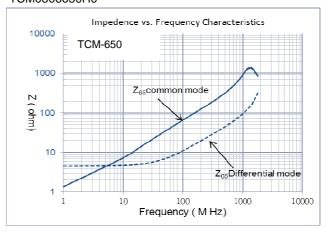
S-Parameter







TCM0806650H0



SOLDER LAND PATTERN

Figure	Symbol	Dimension(mm)
В	А	0.90 ± 0.10
C	В	0.50 ± 0.10
*	С	0.30 ± 0.10
<mark>◆_D</mark>	D	0.30± 0.10



RELIABILITY TEST

Test item	Test condition / Test method	Specification	
Solderability JIS C 0050-4.6 JESD22-B102D Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : $235 \pm 5^{\circ}$ C *Immersion time : 2 ± 0.5 sec *Solder : Sn3Ag0.5Cu for lead-free *Solder bath temperature : $260 \pm 5^{\circ}$ C *Leaching immersion time : 30 ± 0.5 sec *Solder : SN63A	At least 95% of a surface of each termin electrode must be covered by fresh sold Loss of metallization on the edges of each electrode shall not exceed 25%.	
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature : 120~150°C, 1 minute. *Solder temperature : 270±5°C *Immersion time : 10±1 sec *Solder : Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24±2 hrs	Loss of metallization on the edges of each electrode shall not exceed 25%. No mechanical damage. Samples shall satisfy electrical specificatio after test, meet Table 1. Table 1 Appearance No damaged Common Mode Within \pm 20% Impedance Change DC Resistance Within \pm 30% Change	
Drop Test JIS C 0044 Vibration JIS C 0040	*Height: 75 cm *Test Surface: Rigid surface of concrete or steel. *Times: 6 surfaces for each units; 2 times for each side. *Frequency: 10Hz~55Hz~10Hz(1min) *Total amplitude: 1.5mm *Test times: 6hrs.(Two hrs each in three mutually perpendicular directions)	No mechanical damage. Samples shall satisfy electrical specificatio after test, meet Table 1.	
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temperature for 24±2 hours	No mechanical damage. Samples shall satisfy electrical specificate after test, meet Table 2. Table 2 Appearance No damaged DC Resistance Change Within ± 30%	



Temperature cycle JIS C 0025	 30±3 minutes at -40°C±3°C, 10~15 minutes at room temperature, 30±3 minutes at +85°C±3°C, 10~15 minutes at room temperature, Total 100 continuous cycles Measurement to be made after keeping at room temperature for 24±2 hrs 	No mechanical damage. Samples shall satisfy electrical specification after test, meet Table 1.
High temperature JIS C 0021	*Temperature: 85°C±2°C *Test duration: 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test, meet Table 1.
Humidity (steady conditions) JIS C 0022	*Humidity: 90% to 95% R.H. *Temperature: 40±2°C *Time: 1000+24/-0 hrs. Measurement to be made after keeping at room temperature for 24±2 hrs % 500hrs measuring the first data then 1000hrs data	No mechanical damage. Samples shall satisfy electrical specification after test, meet Table 1.
Low temperature JIS C 0020	*Temperature : -40°C±2°C *Test duration : 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test, meet Table 1.



SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

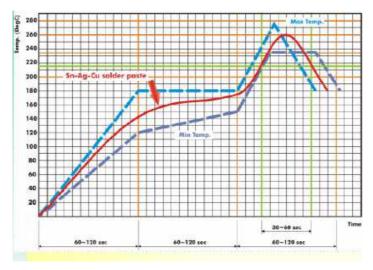


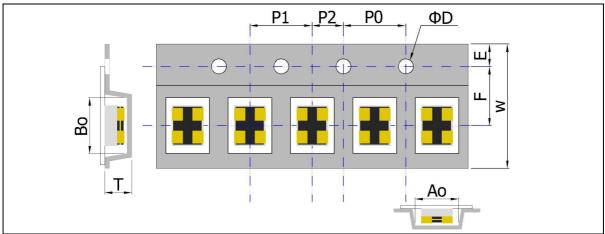
Fig 2. Infrared soldering profile

ORDERING CODE

RG	TCM	0806	650	Н	0	Т
Walsin	Product code	Dimension	СМ	Application	Specification	Packing
RG device	TCM:	code	Impedance	H:	Code from 0~9	T : Reeled
	Thin Film	0806 =	650 : 65 ohm	HDMI/DVI/LVDS	dependent on	
	Common	Length 08		/SATA/PCI-/D-	different electrical	
	Mode Filter	Width 06,		Port	specification	
		,				

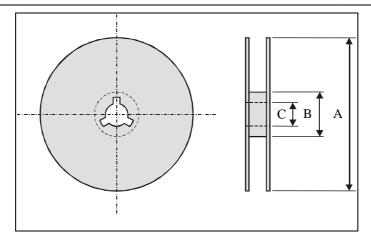
Minimum Ordering Quantity: 10000 pcs per reel.

PACKAGING



Index	A ₀	B ₀	ΦD	Т	W
Dimension(mm)	0.78±0.03	1.04±0.03	1.55±0.05	0.6±0.03	8.0±0.10
Index	Е	F	P_0	P ₁	P_2
Dimension(mm)	1.75±0.05	3.5±0.05	4.0±0.10	4.0±0.10	2.0±0.05

Reel dimensions



Index	А	В	С
Dimension (mm)	Ф178.0	Ф60.0	Ф13.0

Taping Quantity:10000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

Products should be storage in the warehouse on the following conditions.

■ Temperature : -10 to +40°C

Humidity : 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.

单击下面可查看定价,库存,交付和生命周期等信息

>>Walsin Technology(华新科技)